

Title (en)

METHOD AND APPARATUS FOR SOLDERING CIRCUIT BOARDS.

Title (de)

VERFAHREN UND VORRICHTUNG ZUM LÖTEN VON LEITERPLATTEN.

Title (fr)

PROCEDE ET APPAREIL DE BRASAGE DE CARTES DE CIRCUITS.

Publication

**EP 0669857 A4 19960522 (EN)**

Application

**EP 94900343 A 19930920**

Priority

US 9308950 W 19930920

Abstract (en)

[origin: WO9508403A1] A method and apparatus for depositing solder on the terminal pads (10) of printed circuit boards (12) in which a solder resist layer (16) or layers (16, 17) having a thickness corresponding to the desired solder height border the pads. Molten solder from a reservoir (58) is directed by nozzles (72) against the sides of the board (12) to fill the cavities extending above the terminal pads while the board (12) is moving via a conveyor mechanism relative to the reservoir (58). The cavities when filled with molten solder are covered by a suitable element such as a flexible belt (52) or roller. The molten solder within the covered cavities is then cooled below its solidification point and the covering element removed. If desired, part or all of the solder resist layer (16) or layers (16, 17) may then be stripped from the board (12) to leave solder pads extending above the surface of the board (12).

IPC 1-7

**B05D 1/00**

IPC 8 full level

**B23K 3/06** (2006.01); **H05K 3/34** (2006.01)

CPC (source: EP)

**B23K 3/0653** (2013.01); **B23K 3/0692** (2013.01); **H05K 3/3468** (2013.01); **B23K 2101/42** (2018.07); **H05K 3/3452** (2013.01); **H05K 2203/0143** (2013.01); **H05K 2203/0278** (2013.01); **H05K 2203/1509** (2013.01)

Citation (search report)

- [A] US 4493857 A 19850115 - KNIGGE ROLF [DE], et al
- [A] PATENT ABSTRACTS OF JAPAN vol. 014, no. 028 (E - 875) 19 January 1990 (1990-01-19)
- See references of WO 9508403A1

Designated contracting state (EPC)

DE FR GB IT SE

DOCDB simple family (publication)

**WO 9508403 A1 19950330**; AU 5536394 A 19950410; EP 0669857 A1 19950906; EP 0669857 A4 19960522; JP H08504062 A 19960430

DOCDB simple family (application)

**US 9308950 W 19930920**; AU 5536394 A 19930920; EP 94900343 A 19930920; JP 50972995 A 19930920